

MULTIPLE CHIP STACK STRUCTURE AND COOLING SYSTEM

Abstract of the Disclosure

An electronic package comprised of multiple chip stacks attached together to form a single, compact electronic module. The module is hermetically sealed in an enclosure. The enclosure comprises a pressurized, thermally conductive fluid, which is utilized for cooling the enclosed chip stack. A structure that allows for densely-packed, multiple chip stack electronic packages to be manufactured with improved heat dissipation efficiency, thus improving the performance and reliability of the multi-chip electronic packages.

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